

F tL tL tL raL tL a a  
P. Da<sup>a</sup>

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ti/ra a a . Tr ti/ ti/ al a ti/ r -  
a, ti/ . I,  
S<sub>i</sub> Pb a , Pb ti/ a, ti/ al ti/ ti/ a, ti/ ti/ -  
al (165 °C). ti/ ti/ ti/ ti/ -  
ti/ bt/al ti/ ti/ ti/ -  
a, b ti/ ti/ a, Pb al , a, S<sub>i</sub>  
ti/ ti/ ti/ a a, b  
Pb . I, S<sub>i</sub> A , S<sub>i</sub> ti/ a, ti/ . ti/  
ti/ ti/ a, S<sub>i</sub> al, A<sub>3</sub>S<sub>i</sub> ti/ ti/ a -  
E ti/ S<sub>i</sub> a a ti/ al ti/  
ti/ a, a, a ti/ al a .  
C a, ti/ a, UBM WLP ti/ ti/ ti/ a , ti/ WLP  
ti/ ti/ , ti/ a , al ti/ ti/ al , ti/  
I, a UBM al , , ti/ al ti/ al  
ti/ al a , b , ti/ ti/ a a ti/ ti/ UBM  
a . W a ti/ WLP ti/ ti/ , , ti/ -  
al a , b PCB .





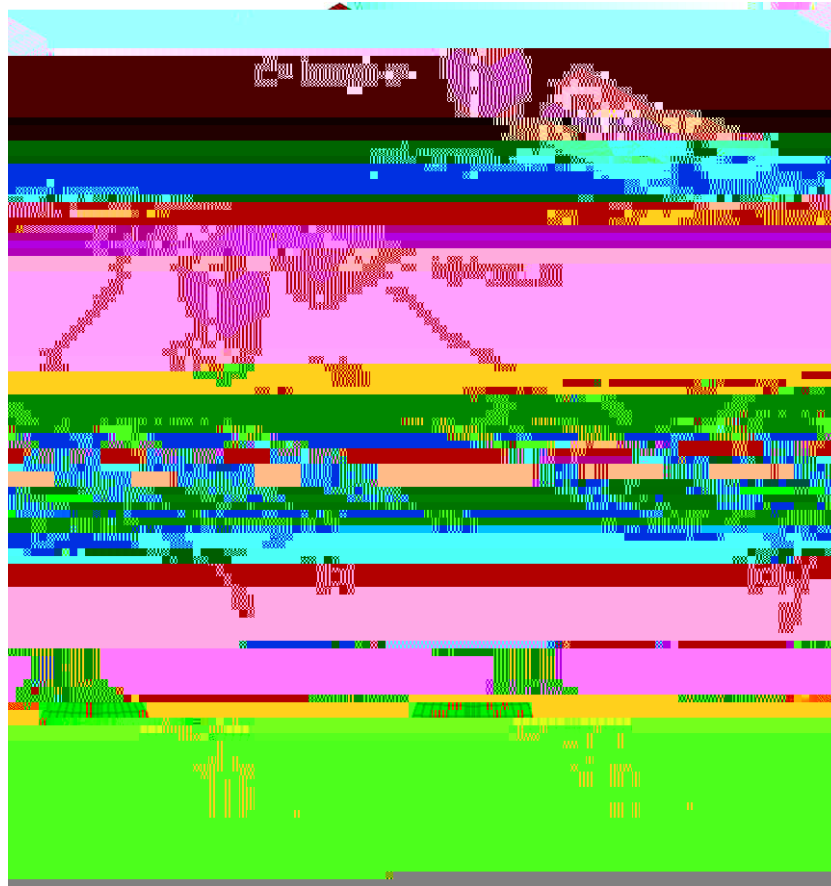


Fig. 8. (a) FEA simulation of the assembly showing temperature distribution. (b) Schematic diagram of the assembly.

The finite element analysis (FEA) simulation of the assembly shows the temperature distribution. The highest temperatures are concentrated around the central component, while the lowest temperatures are at the edges of the PCB. The schematic diagram of the assembly shows the central component, the substrate, and the PCB, with labels indicating the different parts and their connections.

Table 1

Material properties of the assembly [3,9–14].

Parameter	Value	Unit
$E_A$	0.8	V
$Z$	23	
$D_0$	0.027	$2/\mu\text{m}^2$
$Q$	0.0094	V
$\rho_0$	13.3	$\Omega/\mu\text{m}$
$\alpha$	2.8	$1/\text{K}$
$\Omega$	2.72	$3/\mu\text{m}^2$

Table 2

Material properties of the assembly.

Material	Material properties	Value	Unit
PCB	$S$	1.7	$\text{W}/\text{K}$
$S$ (SAC)	$T_r$	57.26	$\text{W}/\text{K}$
$S$	$E$	13.3	$\Omega$
$C$	$T_r$	393	$\text{W}/\text{K}$
$E$	$E$	1.17	$\Omega$

The material properties of the assembly are listed in Table 2. The values are given in the units specified in the table.

## 5. Results

### 5.1. Current density

The current density distribution in the assembly is shown in Figure 9. The highest current densities are concentrated around the central component, while the lowest current densities are at the edges of the PCB. The schematic diagram of the assembly shows the central component, the substrate, and the PCB, with labels indicating the different parts and their connections.

0.139 9 A/ <sup>2</sup>.  
F . 10  
b -b  
b  
a  
F . 10

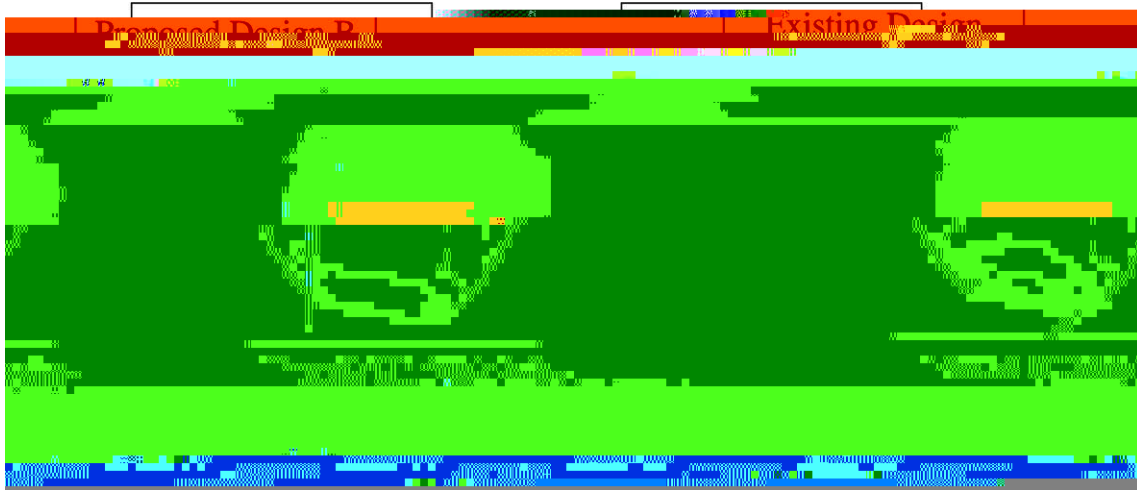


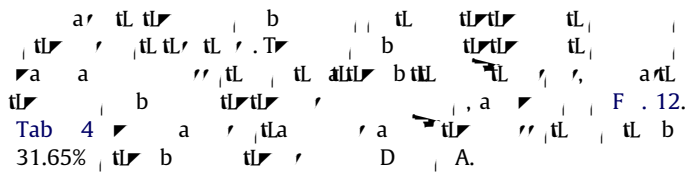
Fig. 11. Comparison of thermal stress distribution between proposed design B and existing design B.

Table 3

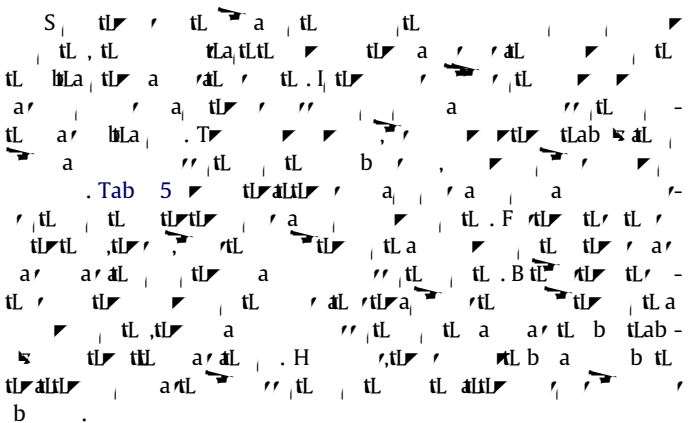
Parameter	Value
Effective thermal conductivity (W/m <sup>2</sup> )	0.1399
Practical thermal conductivity (W/m <sup>2</sup> )	0.1139
% Difference	18.71

Table 4

Parameter	Value
Effective thermal conductivity (W/m <sup>2</sup> )	0.1399
Practical thermal conductivity (W/m <sup>2</sup> )	0.958
% Difference	31.65



5.3. Mesh dependency



5.2. Temperature distribution

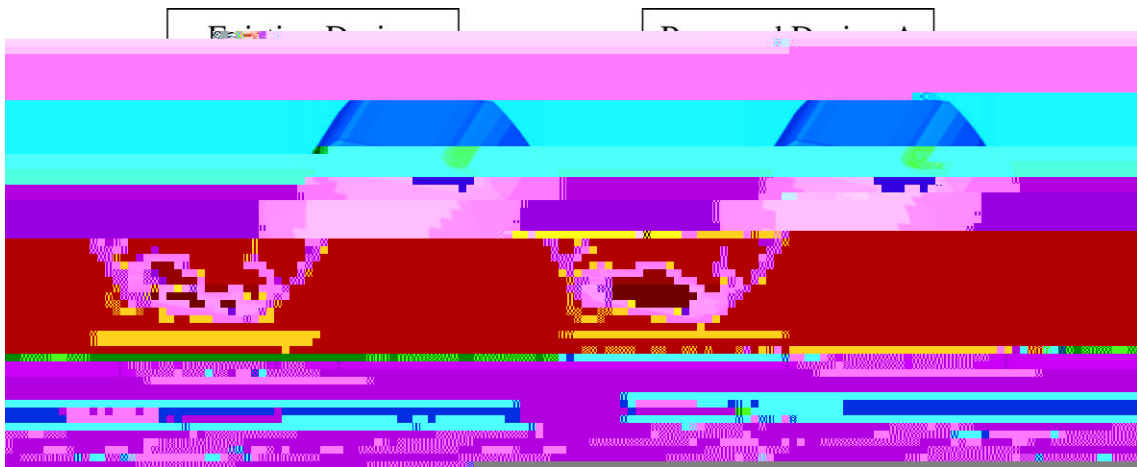
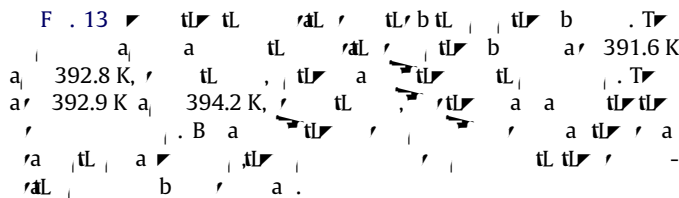


Fig. 12. Comparison of thermal stress distribution between proposed design A and existing design A.

#### 5.4. Divergence analysis

$\nabla \cdot \mathbf{a} = \frac{\partial a_i}{\partial x_i} = \frac{\partial}{\partial x_i} (a_i) = \frac{\partial}{\partial x_i} (a_i)$



